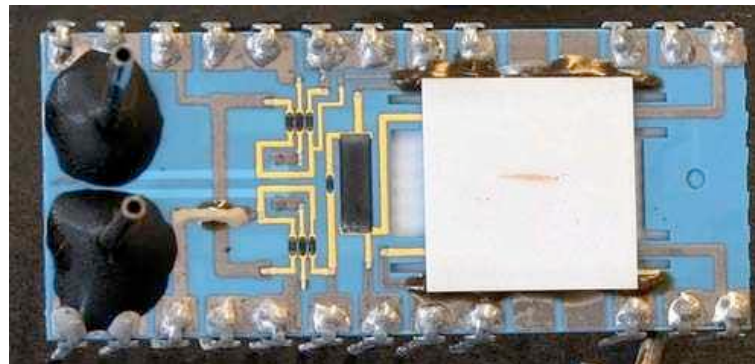


Integrated calorimetric microreactor in low-temperature cofired ceramic (LTCC) technology

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Object of this work

Explore the feasibility of an LTCC microreactor

- Chemical stability: compatible with HCl, NaOH, ...
- Thermal stability to $>100^{\circ}\text{C}$

Achieve a high degree of integration

- Temperature measurement
- Reactant flow measurement
- Temperature control
- Calorimetric chamber

Outline

- **Introduction**
- **Flow meter**
- **Microreactor**
- **Preliminary characterisation**

Features of microreactors

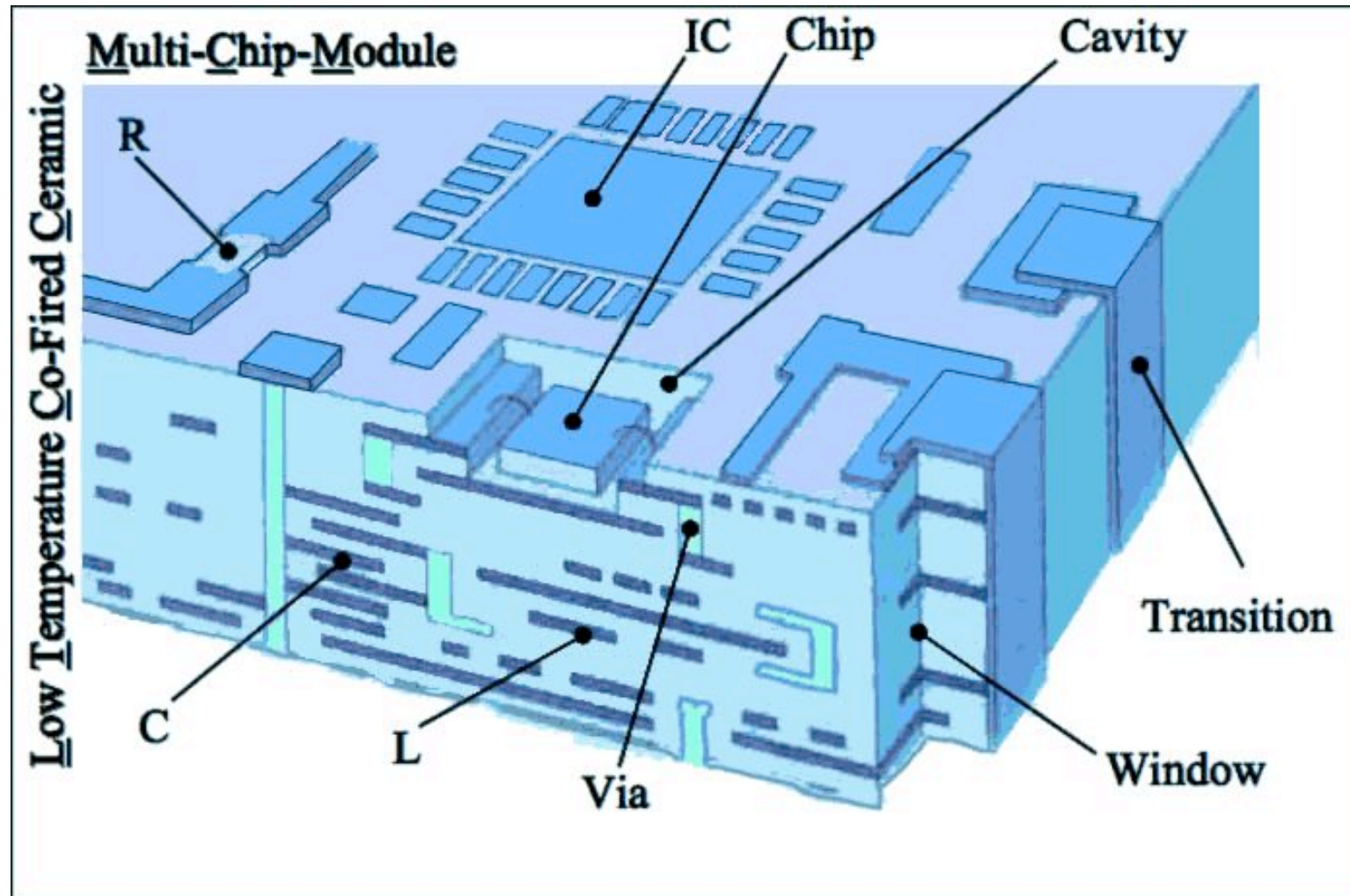
- Very strong thermal coupling
- Safe study of very exothermic reactions
- Efficient mixing by diffusion (small channels)
- Control of residence time
- Equivalent to plug flow (usually)



LTCC technology

- **Low-Temperature Cofired Ceramic**
- Originally for electronics
 - Radio frequency (RF): Bluetooth modules
 - Car electronics: engine control, ABS, etc.
- High reliability
- Hermeticity
- Thermal ($>600^{\circ}\text{C}$) & chemical stability

LTCC electronics modules



What is LTCC?

- Calcium aluminosilicate + Mg, Na, ...
- Obtained by firing tapes of glass + filler
- Cofired with itself & thick-film materials

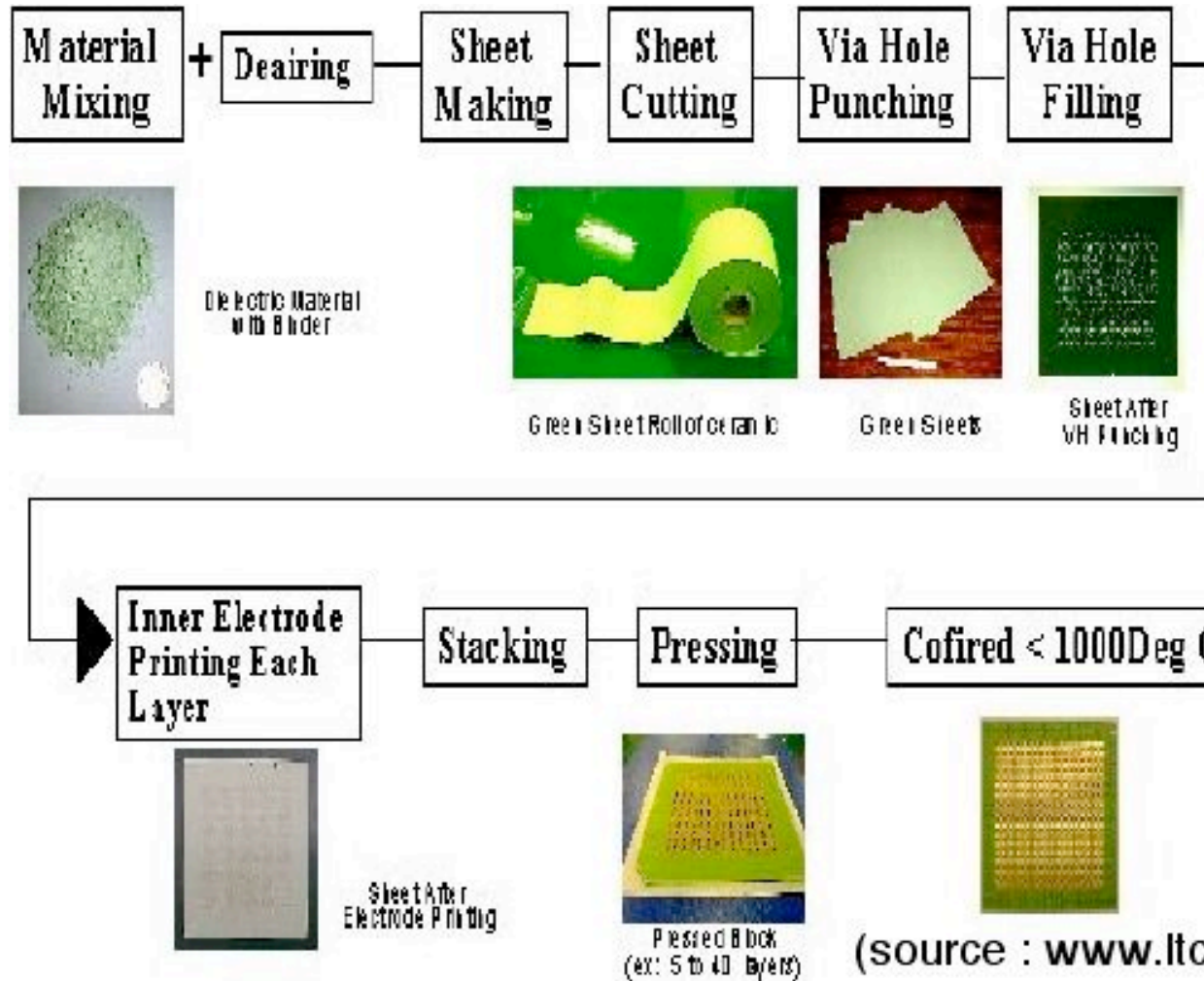
	COMPONENTS		
	SUBSTRATE	PASSIVES	
Components	Tape	Conductor	Resistor
Function	Dielectric layer	Thick-film paste	Thick-film paste
Functional group	Dielectric powder	Precious metal, fine size powder	Conductive oxide, fine size powder
Glass	<ul style="list-style-type: none"> ⌘ Lowers T_{firing} ⌘ increases dielectric strength and density 	<ul style="list-style-type: none"> ⌘ Lowers T_{firing} ⌘ increases adhesion to substrate and density 	<ul style="list-style-type: none"> ⌘ Lowers T_{firing} ⌘ increases density ⌘ surrounds conductive powder
Organics	Binder, solvent, dispersant for appropriate rheology		

LTCC physical properties

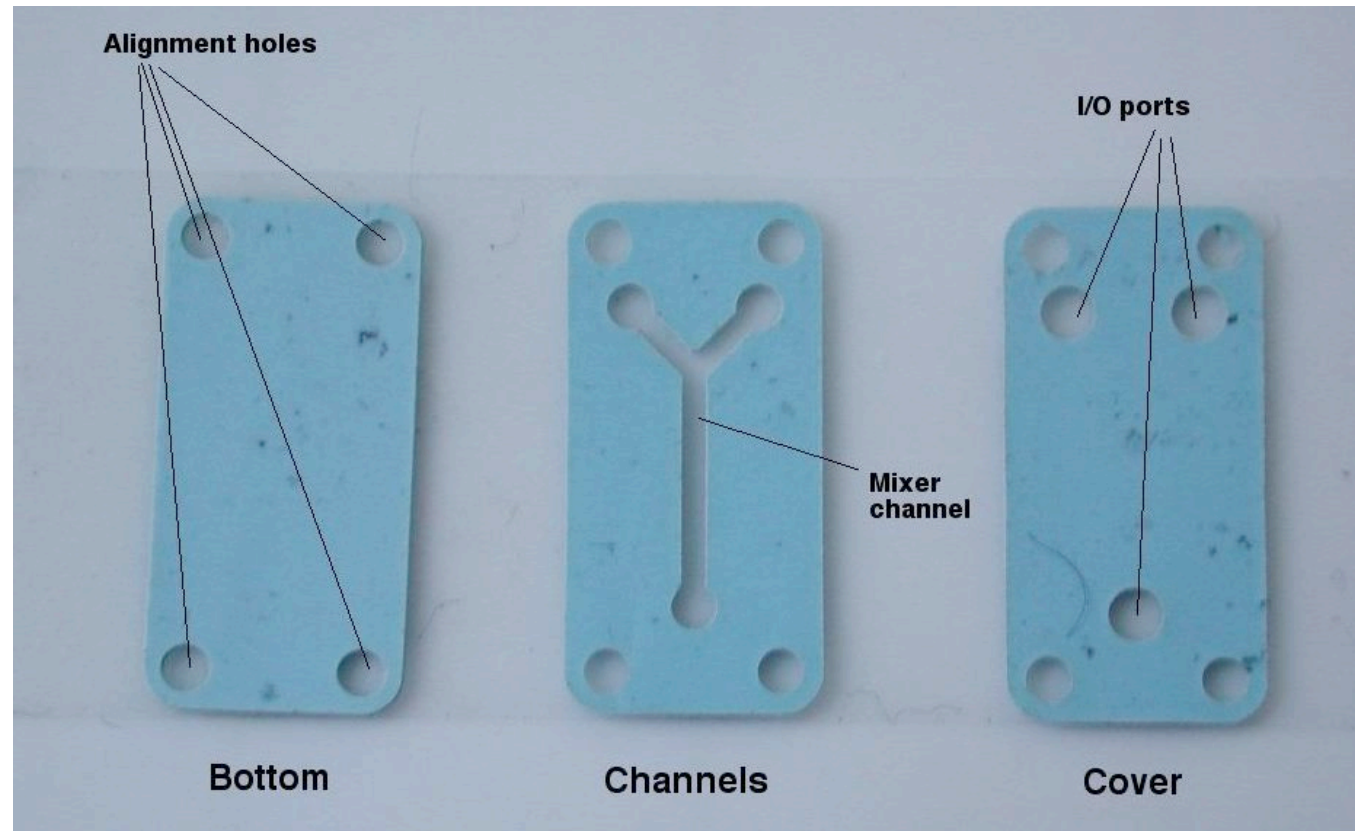
- Relatively low thermal conductivity
- Can be enhanced by using Ag thick films

	LTCC* (DP951)	Al ₂ O ₃ 96%	Al ₂ O ₃ ⁺ pure	BeO 99.5%	AlN 98%	ZrO ₂
MECHANICAL CHARACTERISTICS						
Flexural Strength (MPa)	320	274	300-400	241	340	980
Young's Modulus (GPa)	120	314	400	343	340	206
Density	3.1	3.8	-	2.8	3.3	6
THERMAL CHARACTERISTICS						
Thermal expansion coefficient (10 ⁻⁶ / °C)	5.8	7.1	8.1	7.5	4.6	10.5
Thermal Conductivity (W/mK) and (25-300)°C	3	20.9	-	251	180	3.8
ELECTRICAL CHARACTERISTICS						
Rel. dielectric constant (@1MHz)	7.8 @10MHz	9.6	-	6.5	8.6	8.5
Dissipation factor (x10 ⁻⁴) @10MHz	0.15% @10MHz	3	-	2	5	-

LTCC process flow

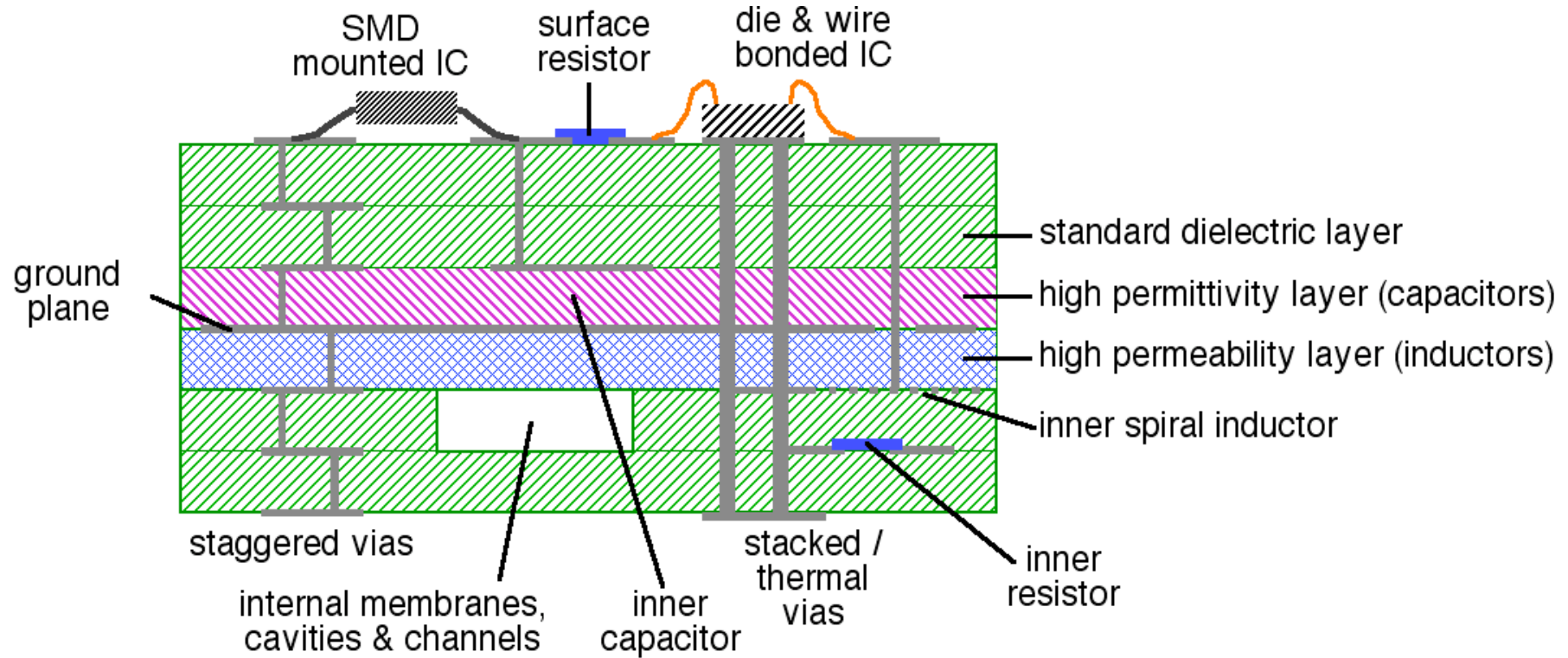


Why LTCC (1) ?



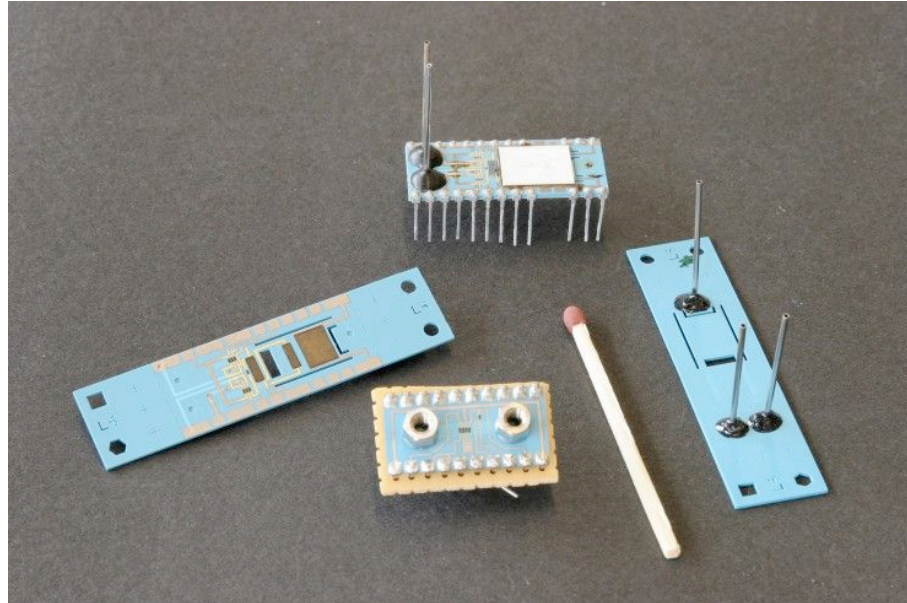
- Ease of structuration

Why LTCC (2) ?



- Integration of many functions

Why LTCC (3) ?



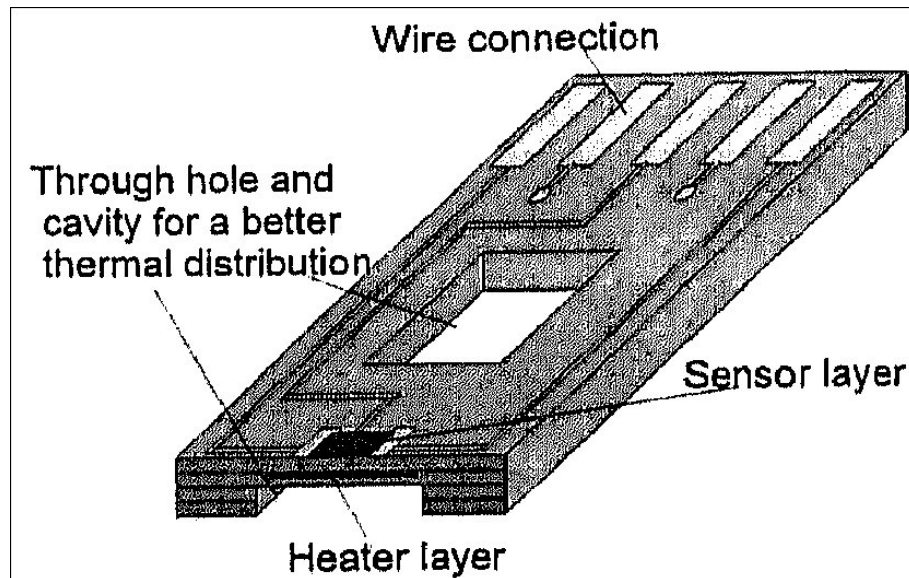
- Microreactor & flow sensor

Why LTCC (3) ?



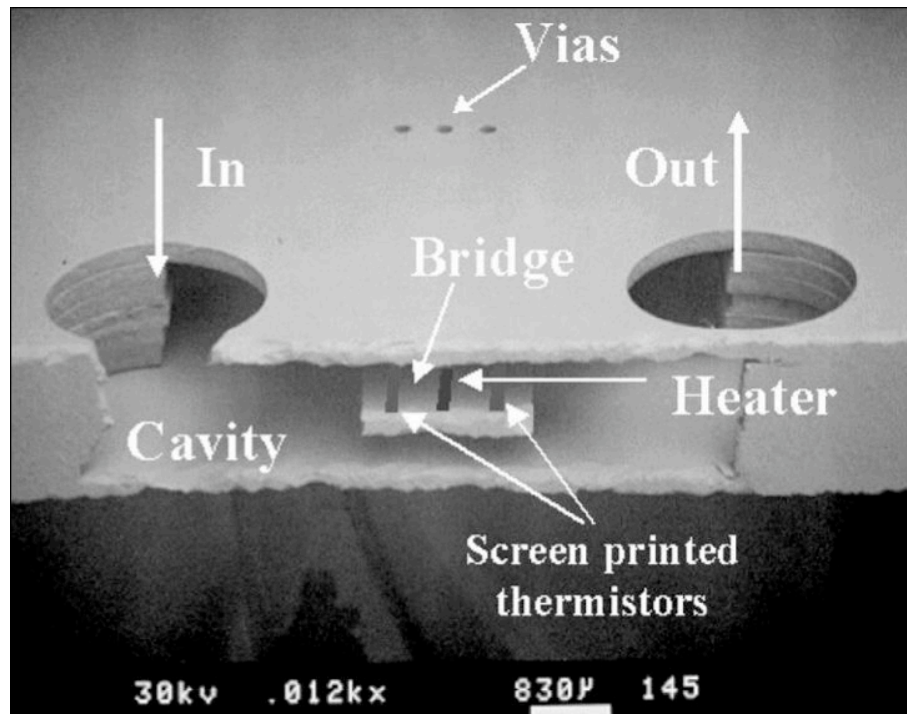
- Microreactor & flow sensor
- Inclination sensor

Why LTCC (3) ?



- Microreactor & flow sensor
- Inclination sensor
- Gas sensor (Golonka et al., 1998)

Why LTCC (3) ?

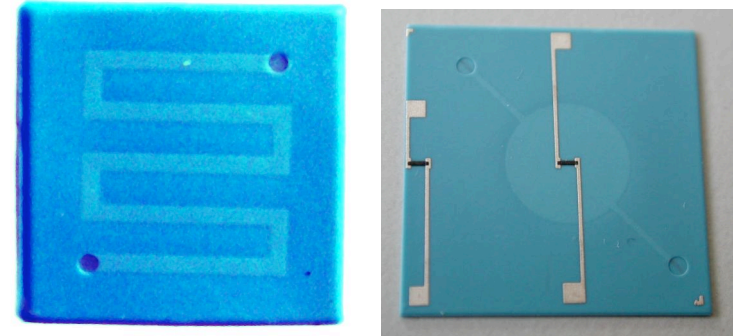


- Microreactor & flow sensor
- Inclination sensor
- Gas sensor (Golonka et al., 1998)
- Flow sensor (Gongora et al., 2001)

LTCC fluidics

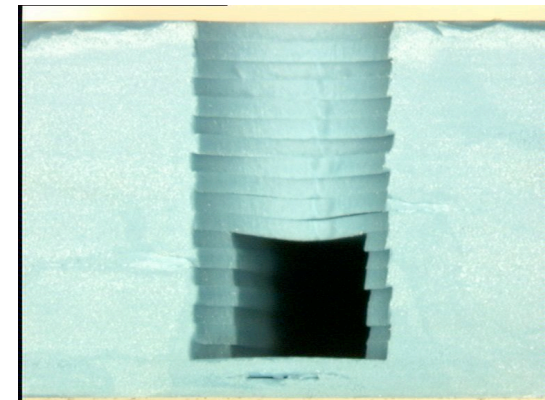
Graphite fugitive phase

- Small height ($\approx 10 \mu\text{m}$)
- For gases essentially
- Structures defined by printing

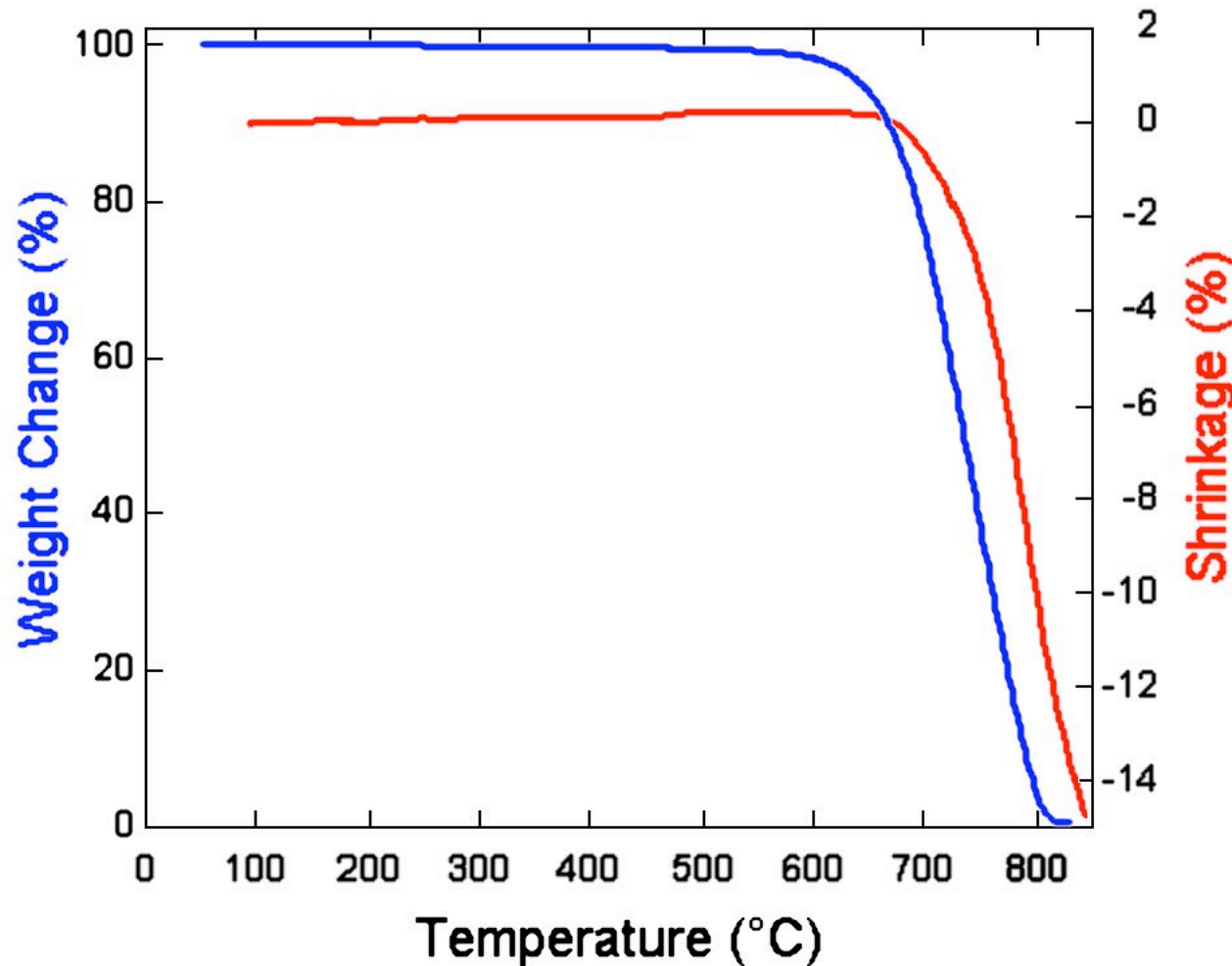


Laser cutting

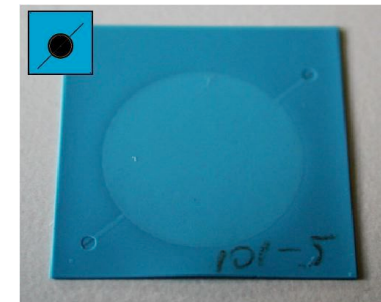
- Larger height ($\approx 100 \mu\text{m}$)
- Structures defined by cutting
- Retained solution for this project



Cavities by graphite fugitive phase

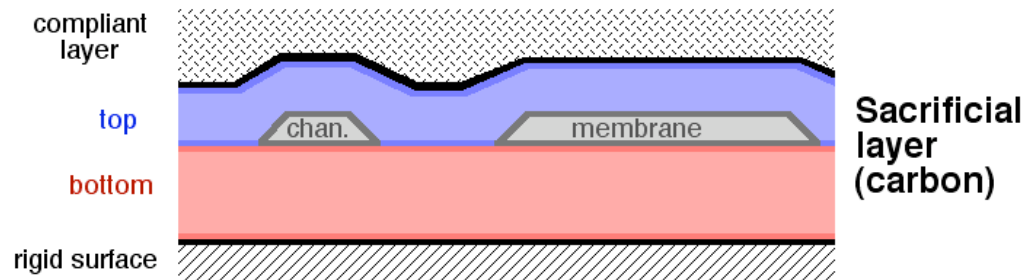
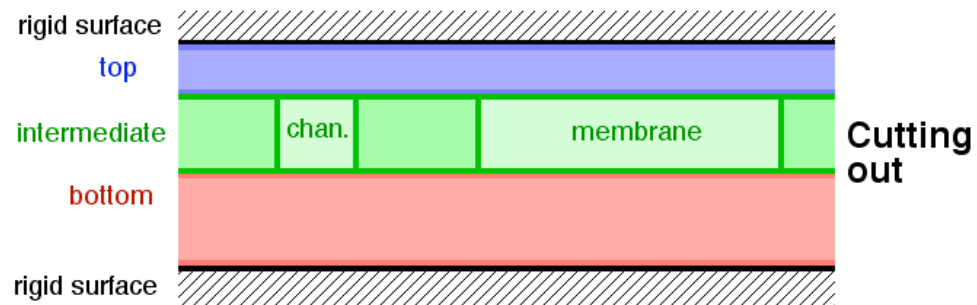


- Graphite burns out **shortly before** LTCC densifies.
- Spacing can be controlled by **heating rate**.

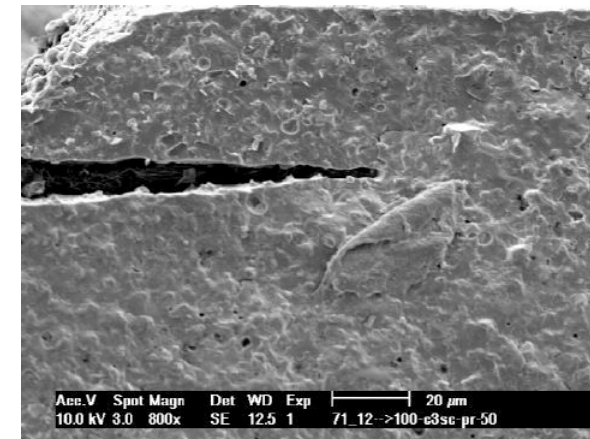
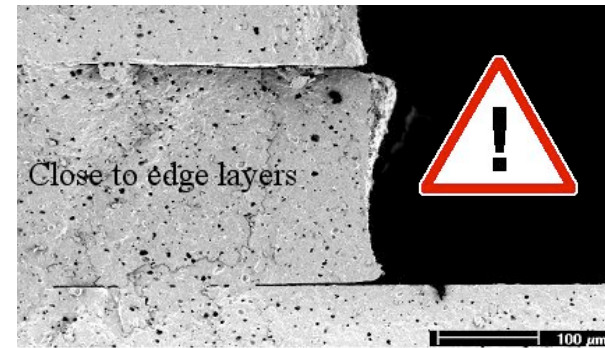


Comparison of methods - process

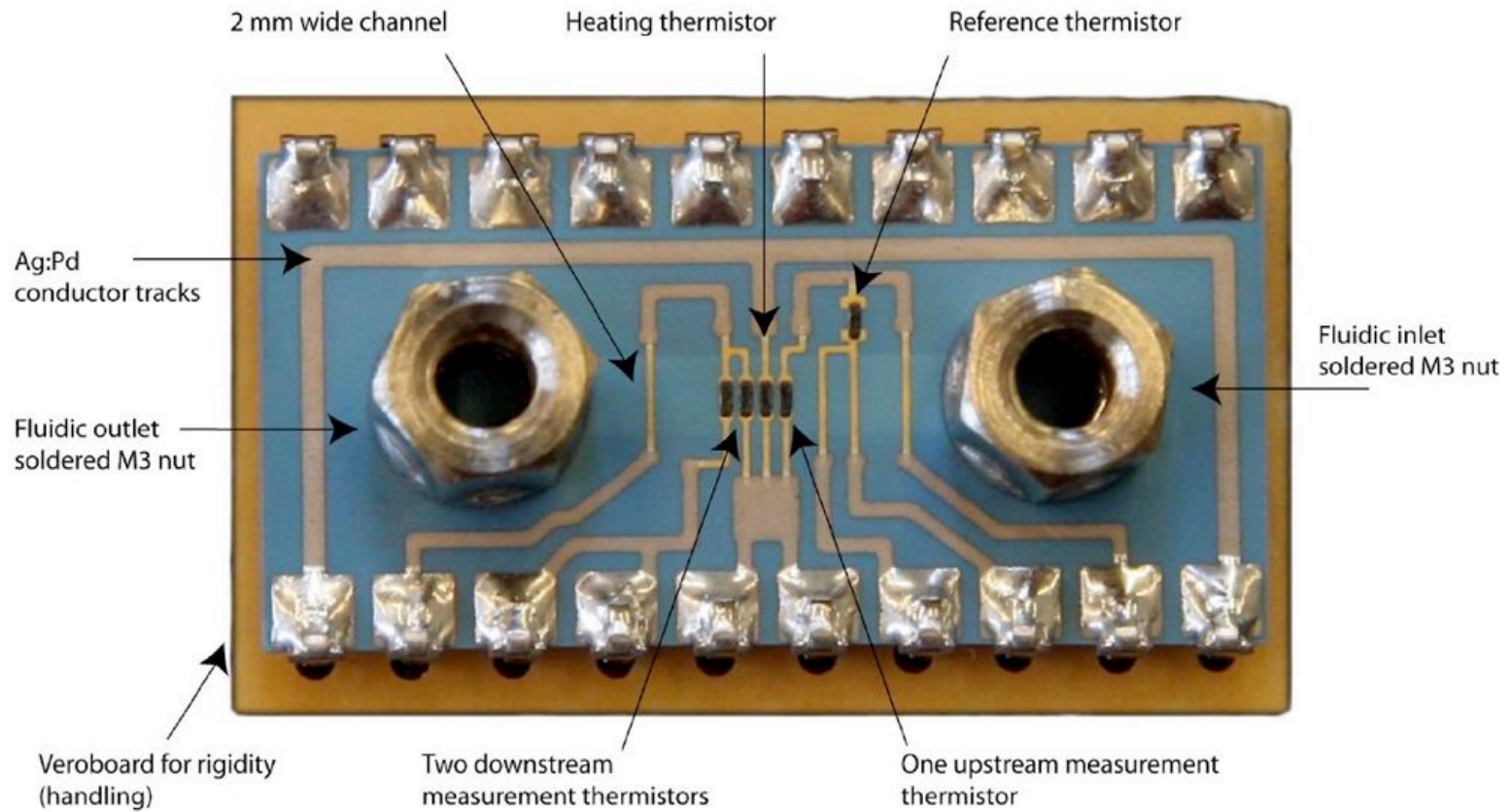
Processing



Properties



Flowmeter

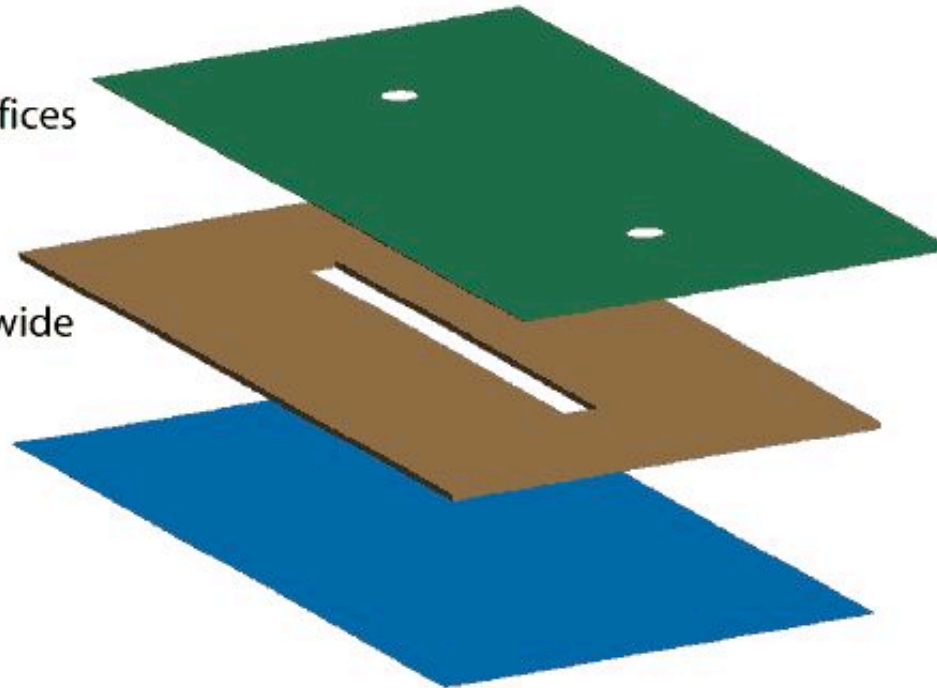


Flowmeter - structure

Top layer (40 μm)
with $\varnothing 1$ mm fluidic orifices

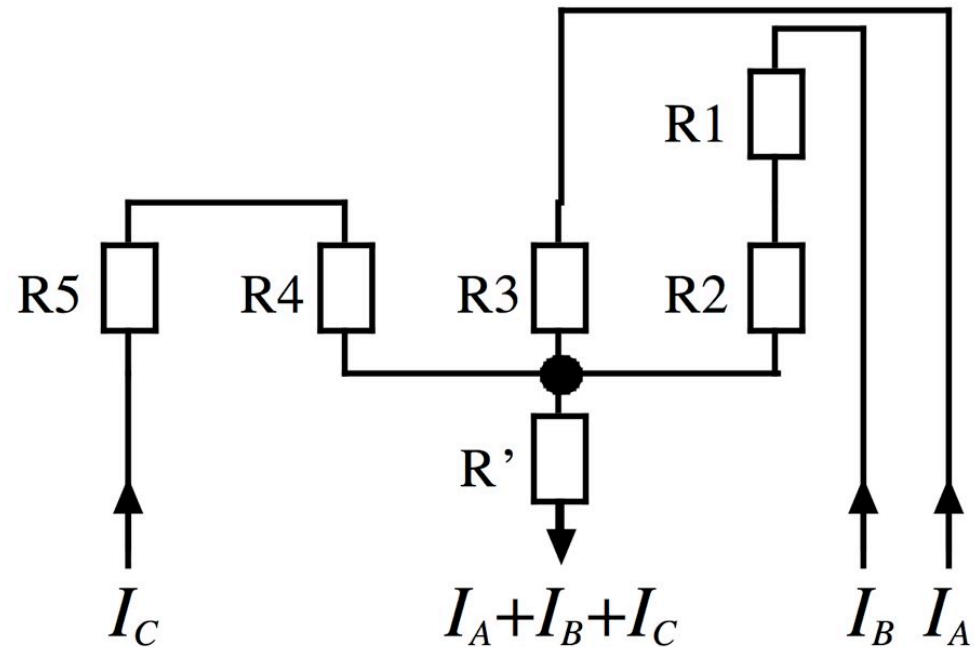
Middle layer (200 μm)
with channel 1-2 mm wide

Bottom layer (40 μm)
25.4 x 12.7 mm



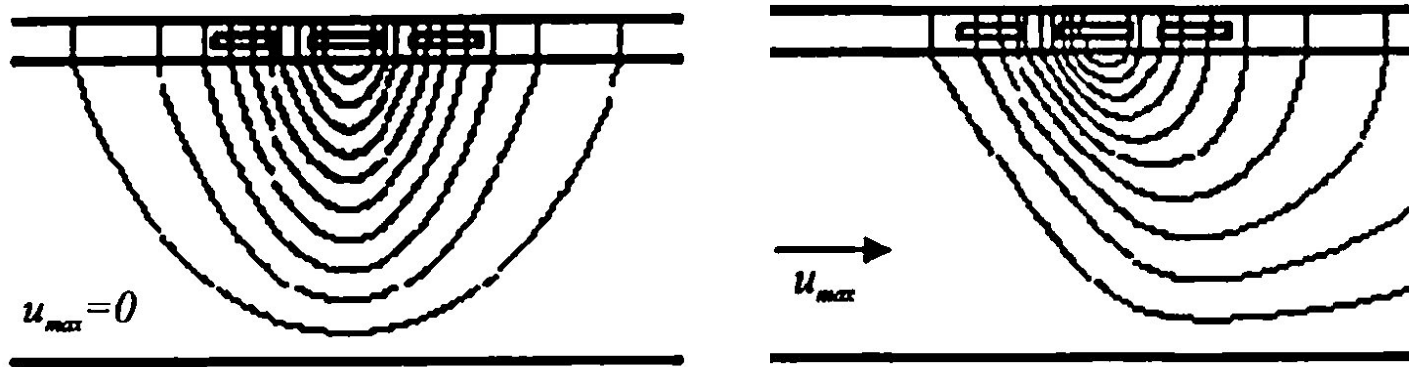
- Simplest structure
- Good start for LTCC processing

Flowmeter - electrical



- All resistors are thick-film PTC thermistors
- Here, resistors are *post-fired* (process compatibility)

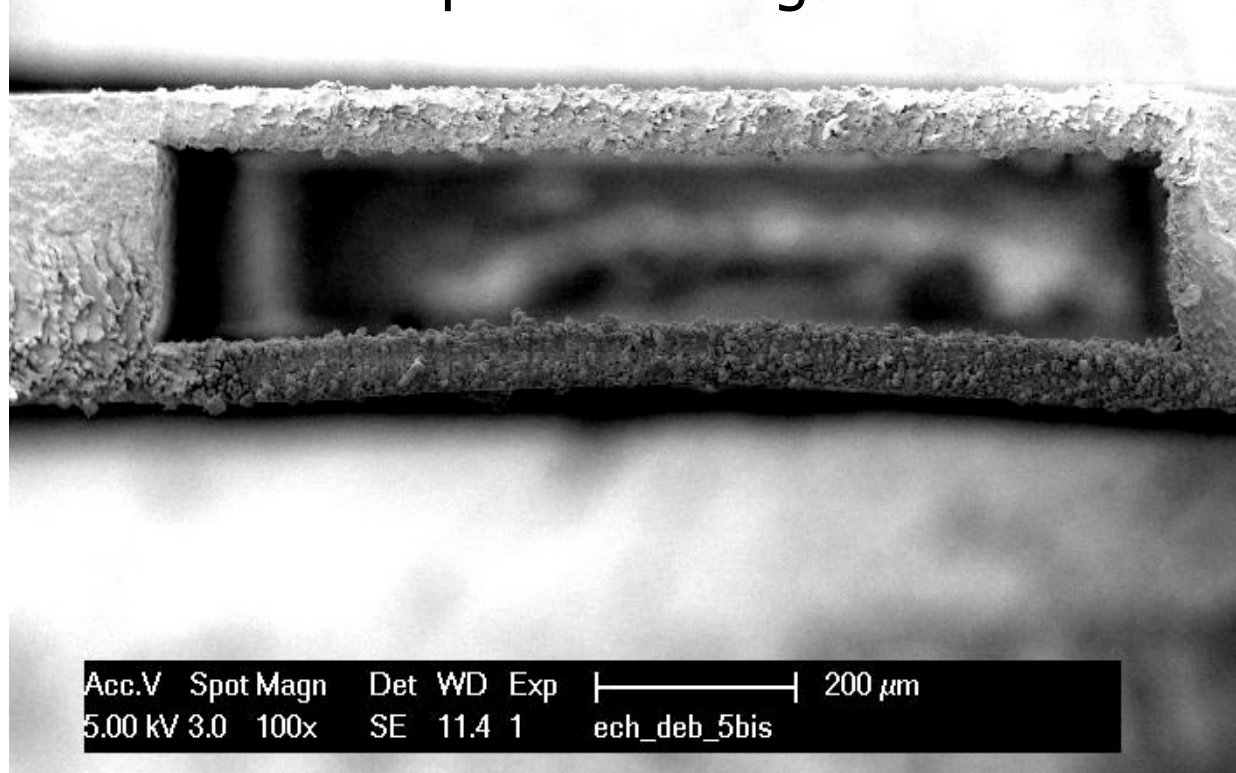
Flowmeter - principle



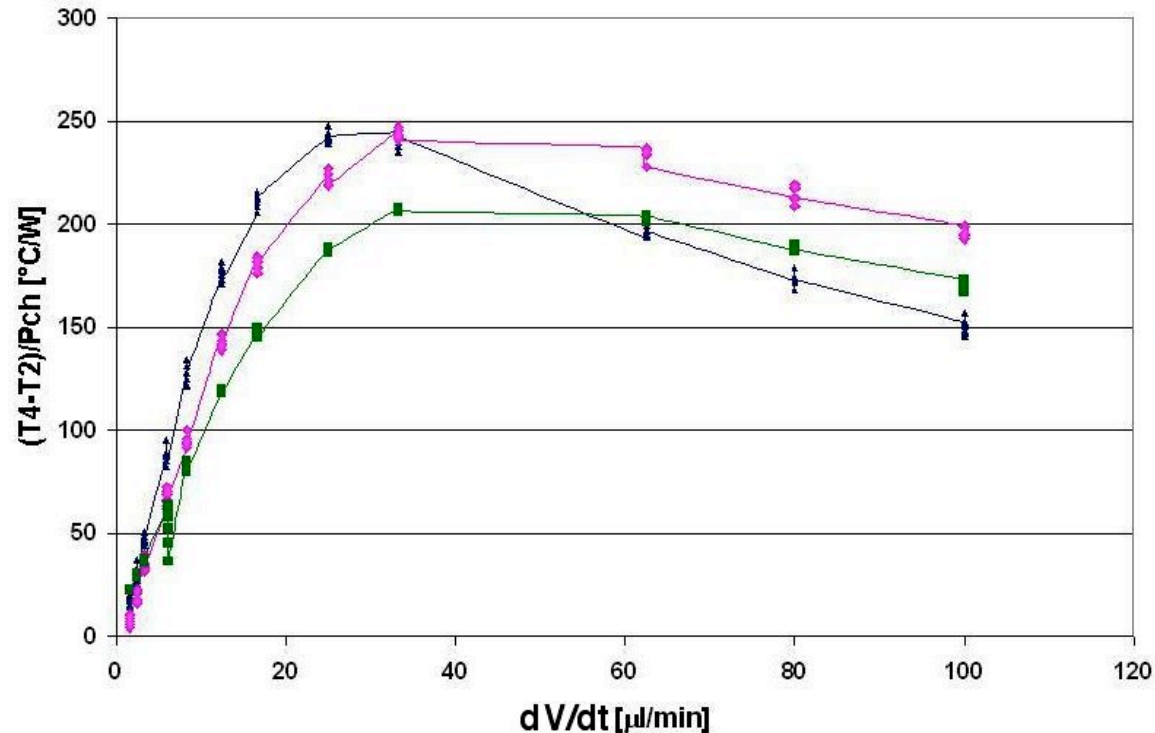
- Flow = 0: symmetrical temperature profile
- Flow \neq 0: downstream resistor hotter than upstream
- Very large flow: use heat loss

Flowmeter - channel

- Good integrity
- Slight deformation upon sintering

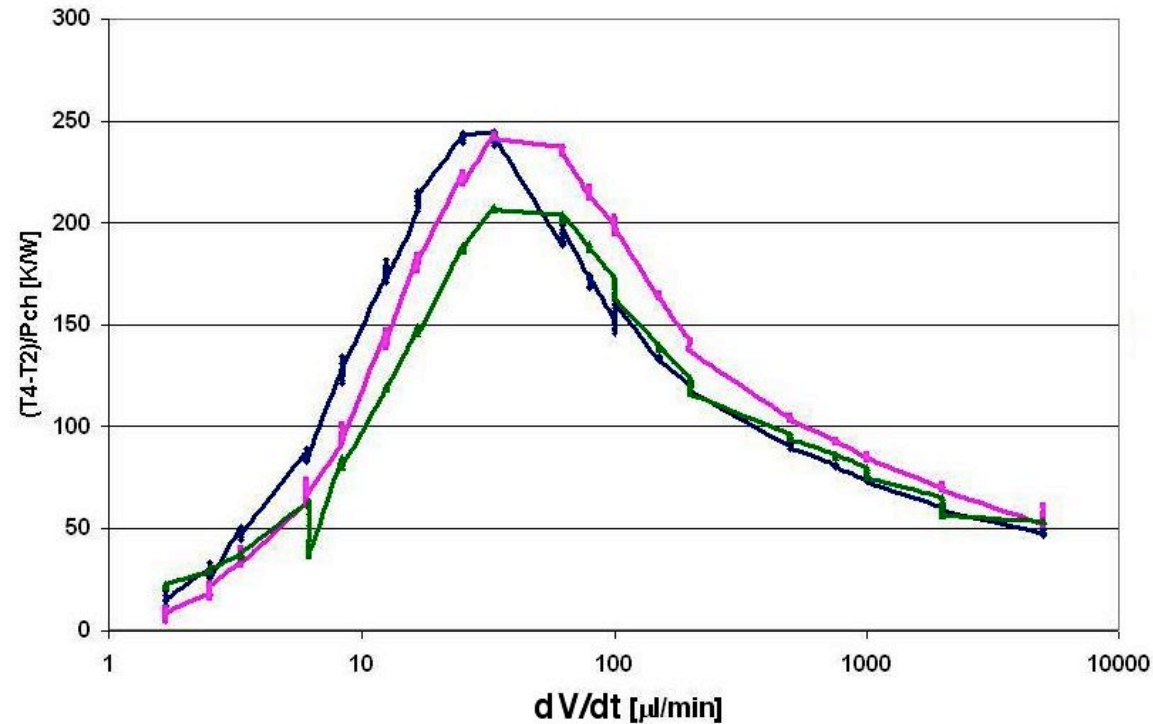


Flowmeter - results @ low flow



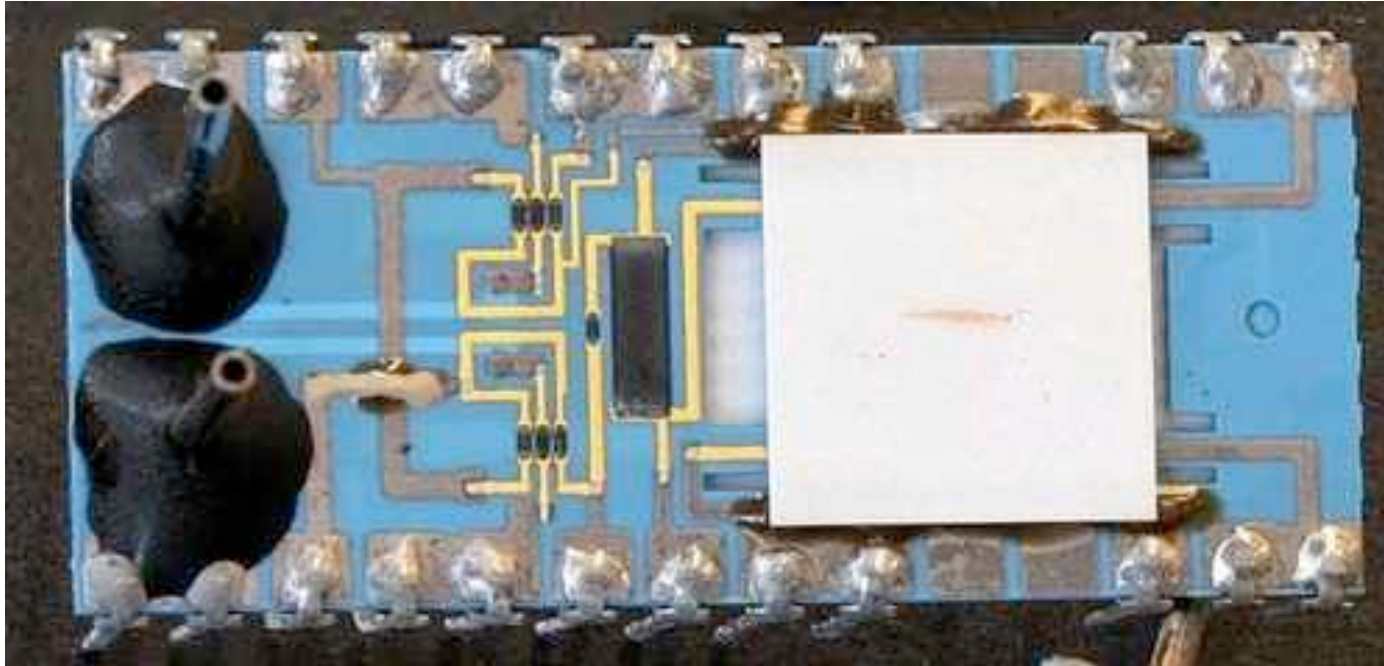
- **Low flows:** increase in dissymetry with flow
- **Large flows:** decrease of signal due to heat loss

Flowmeter - results @ high flow



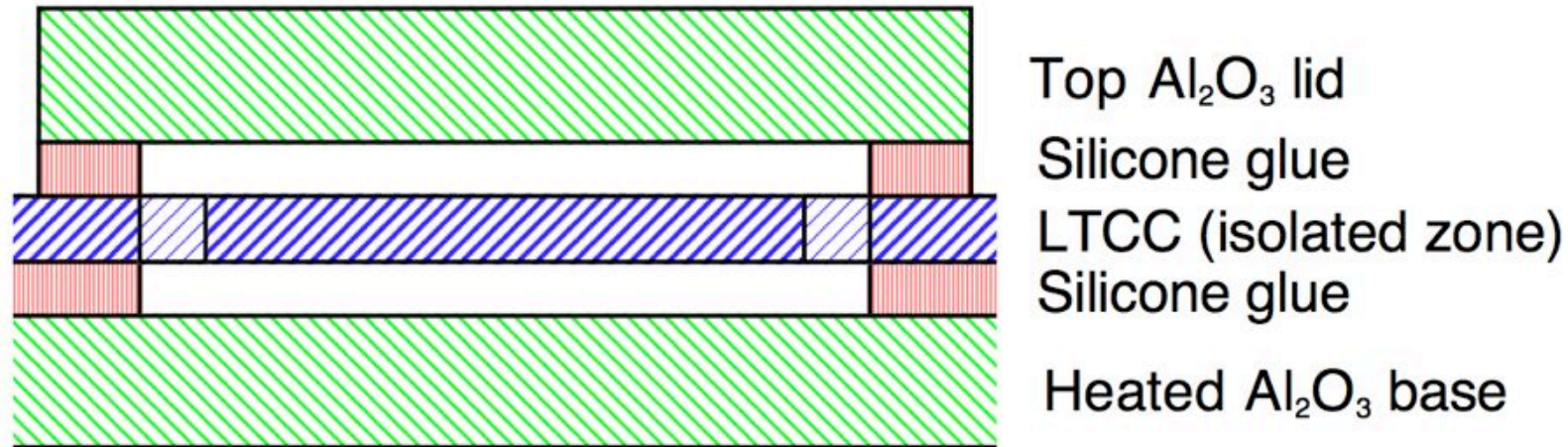
- **Low flows:** increase in dissymetry with flow
- **Large flows:** decrease of signal due to heat loss

Microreactor / calorimeter



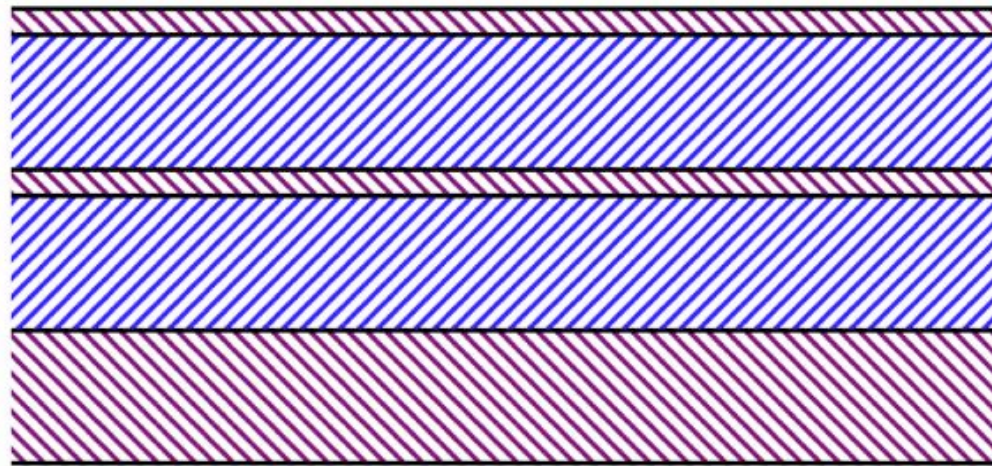
- 2 flowmeters (similar design), one for each reactant
- Control of temperature
- Measurement of heat of reaction

Microreactor - design (1)



- Isolated & enclosed reaction zone
- Well-defined thermal resistance to enclosure
- Steady state heat power = $\Delta T / R_{th}$
- Calibration of R_{th} by calibration heating resistor

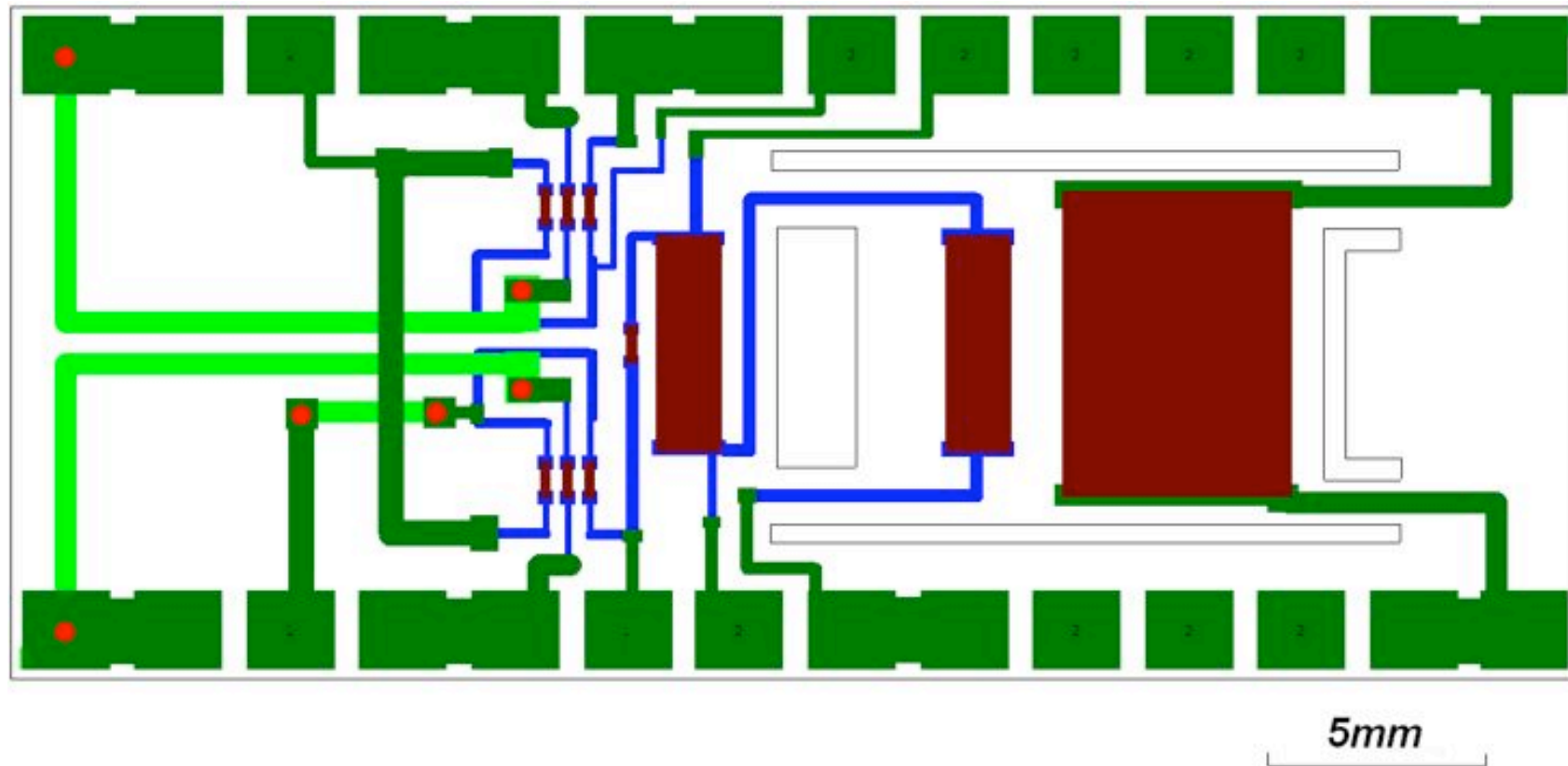
Microreactor - design (2)



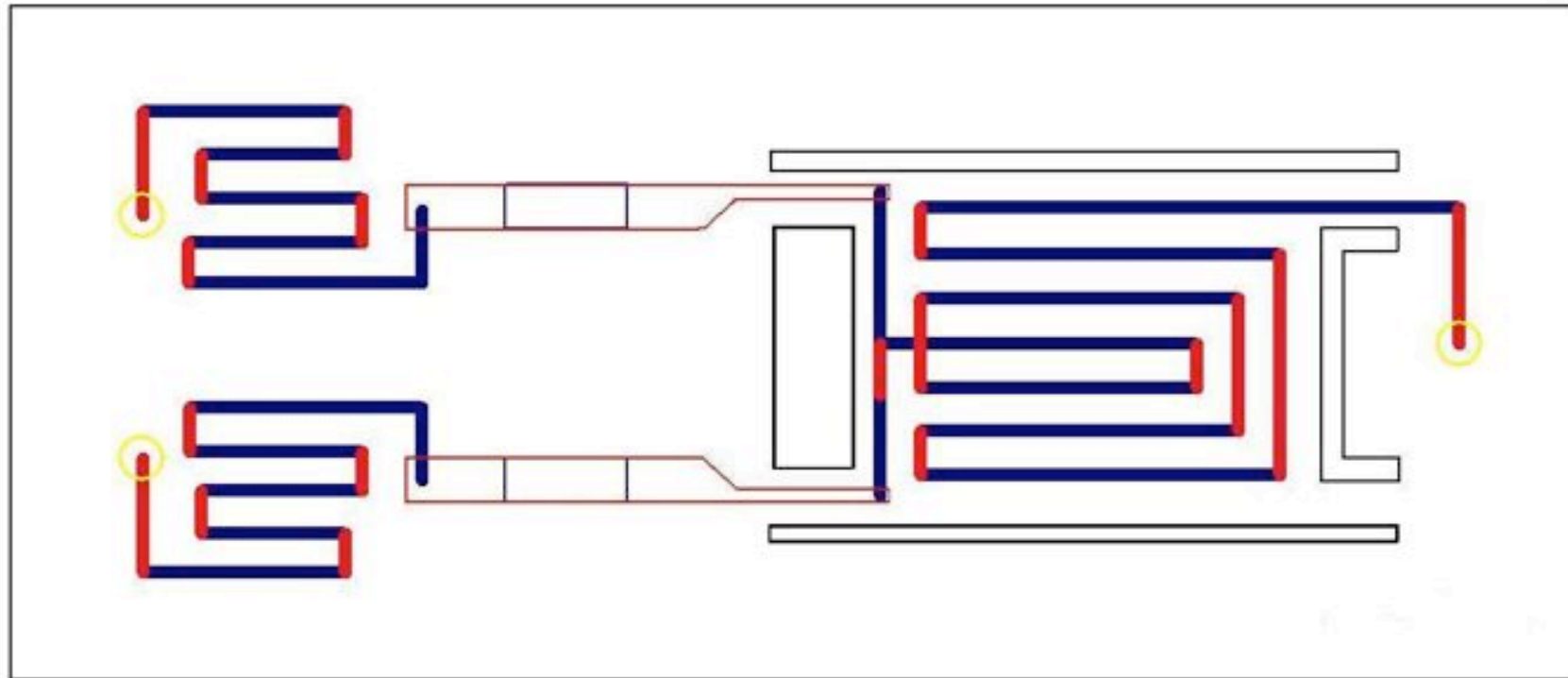
Top lid
Top fluidic layer
Separator
Bottom fluidic layer
Bottom (base)

- Total 5 LTCC layers

Microreactor - electrical circuit

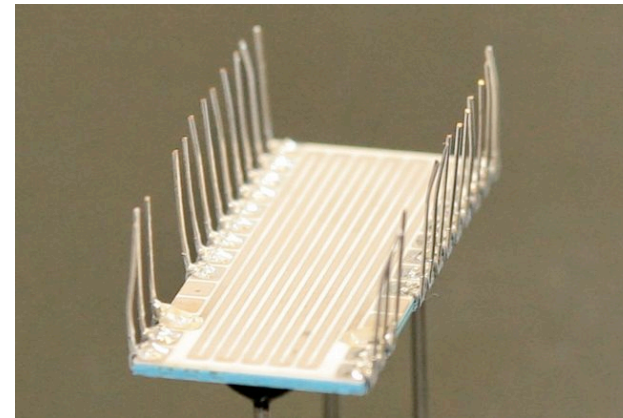
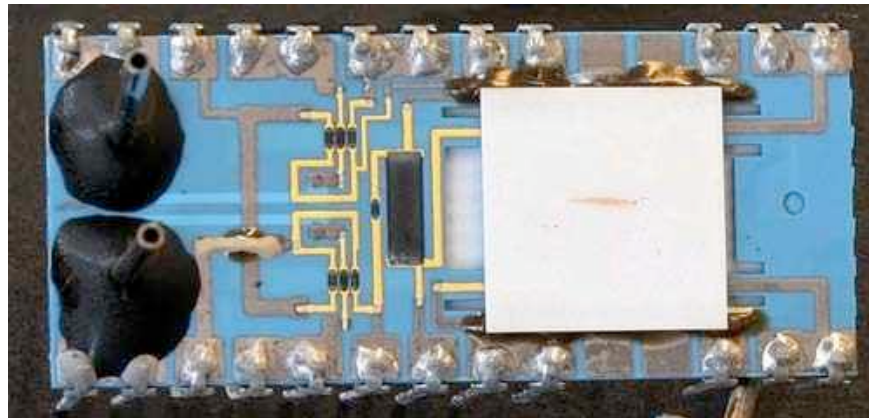
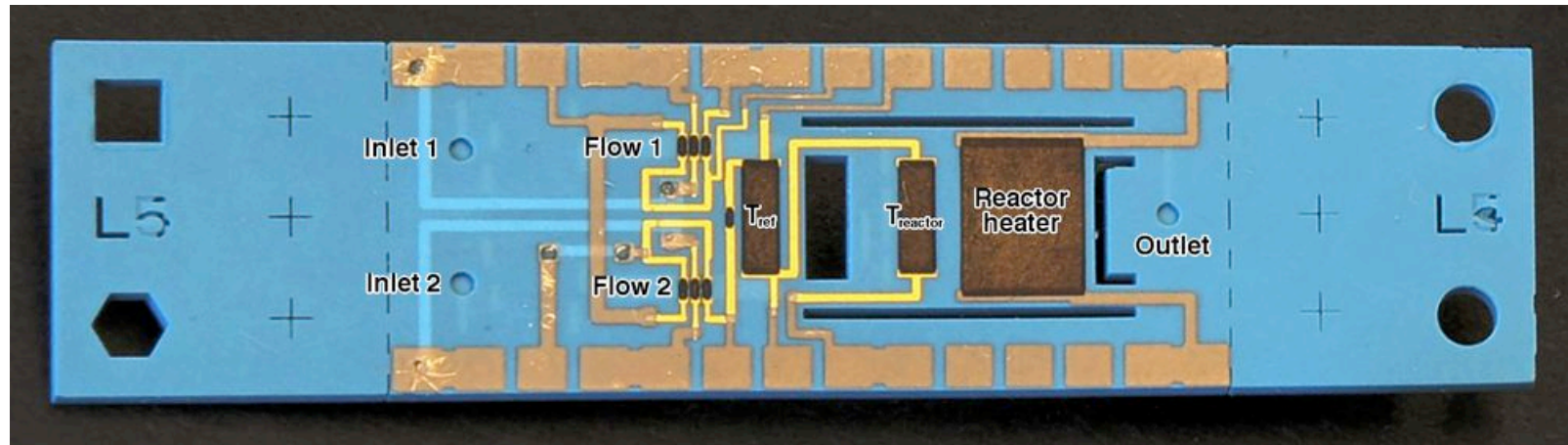


Microreactor - fluidic circuit

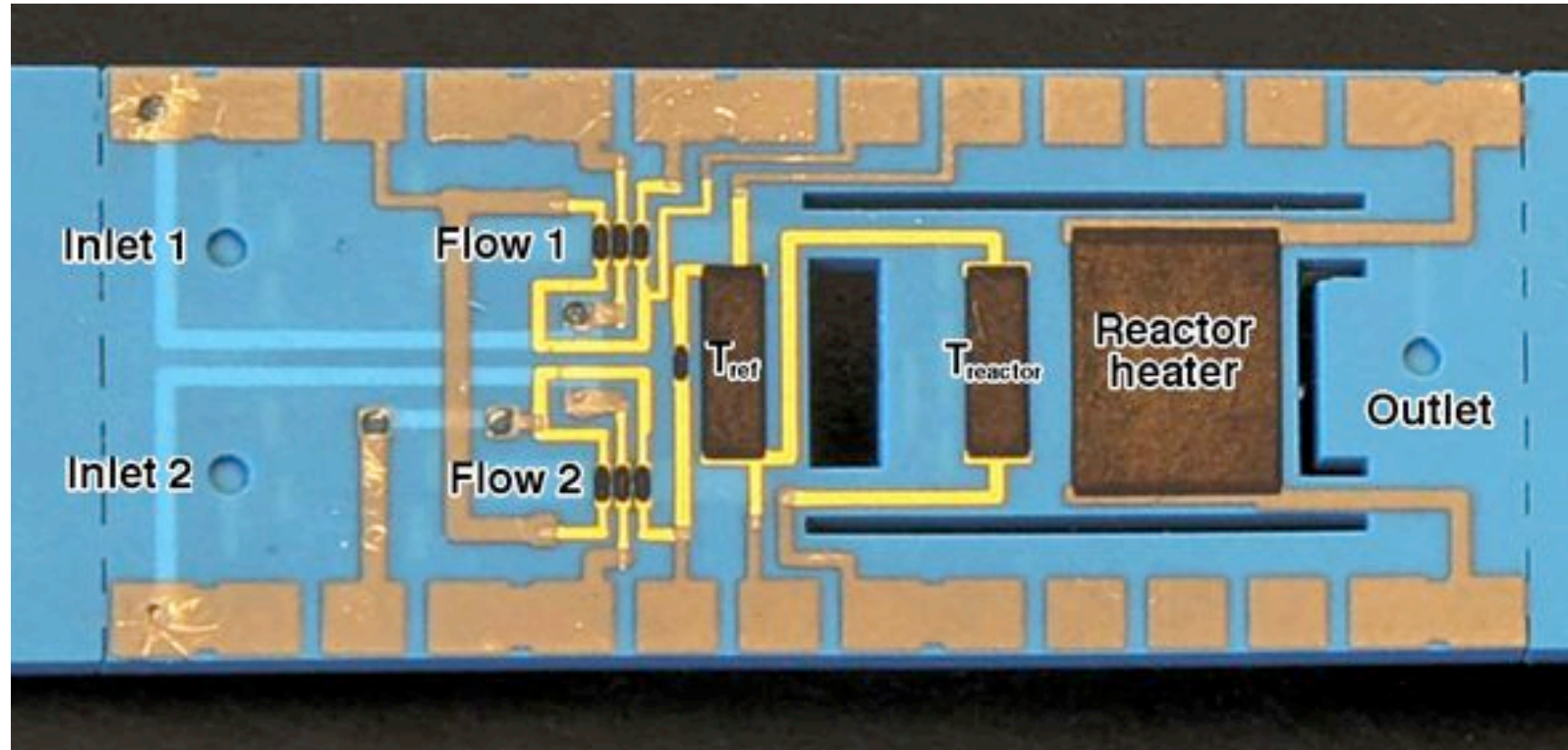


*Dimensions : 35.55*15.25mm*

Microreactor - LTCC (1)

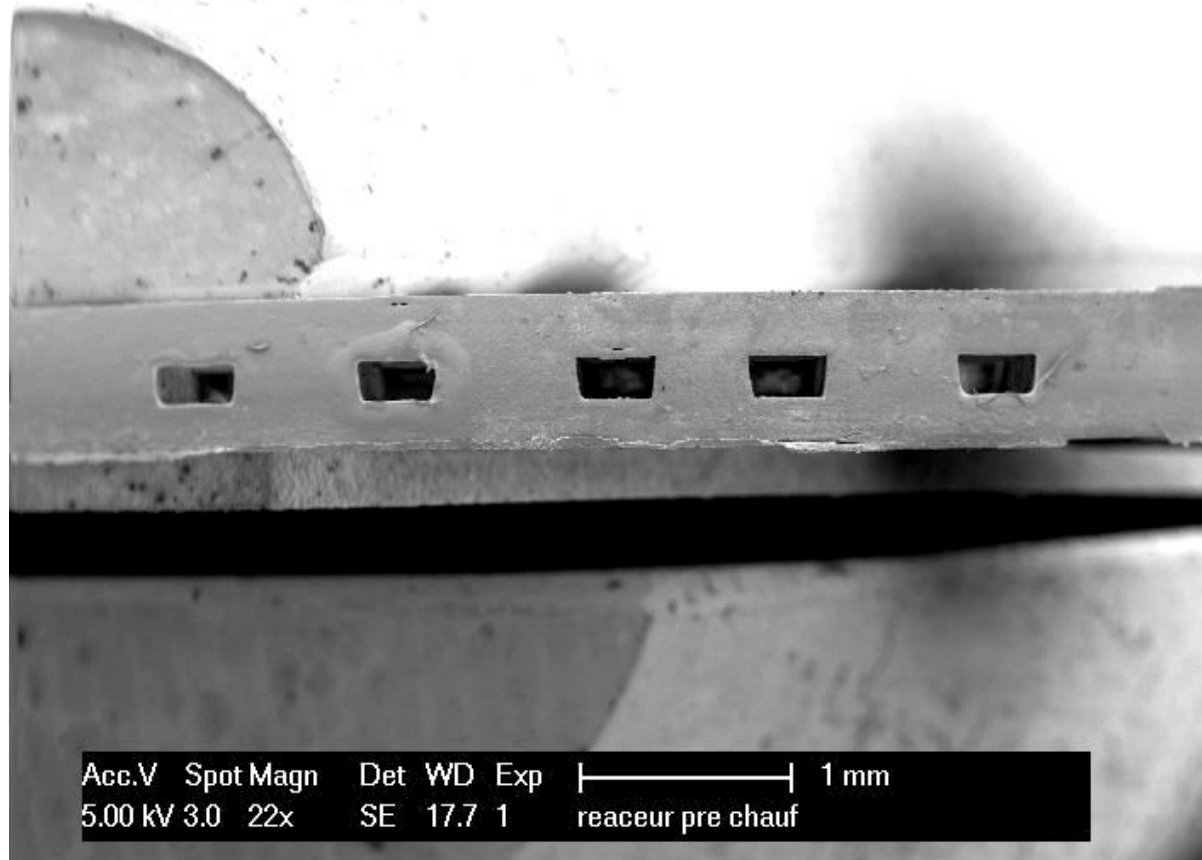


Microreactor - LTCC (2)

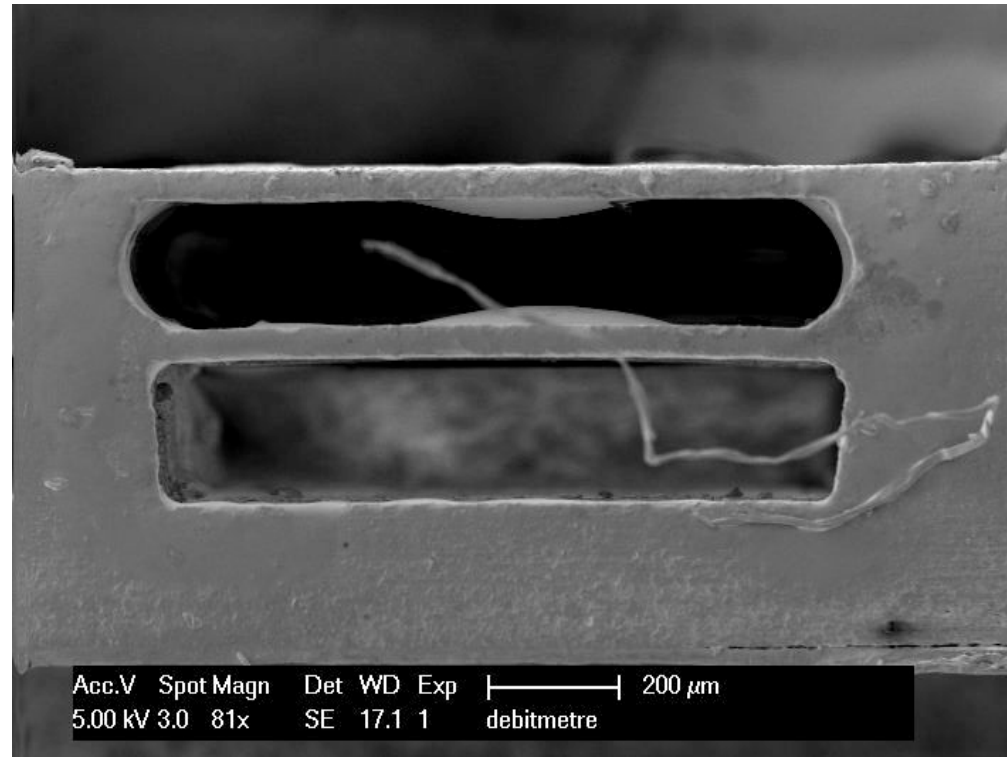


Microreactor - microscopy (1)

- Meanders in pre-heating zones



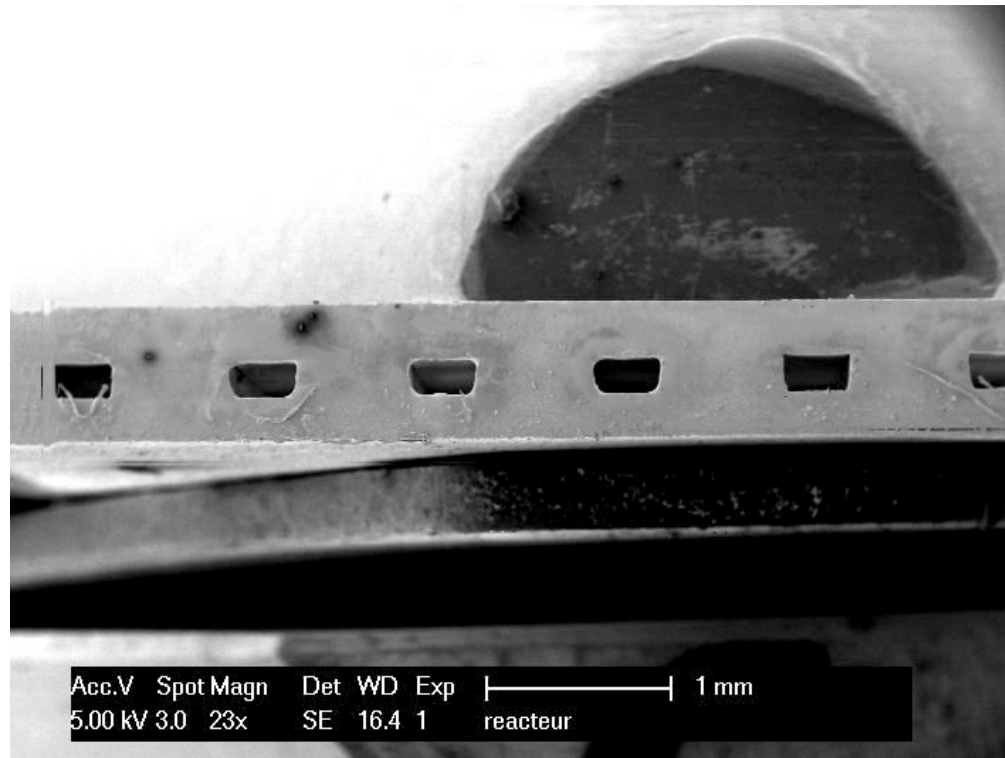
Microreactor - microscopy (2)



- Top cavity: flowmeter channel
- Bottom cavity: thermal insulation

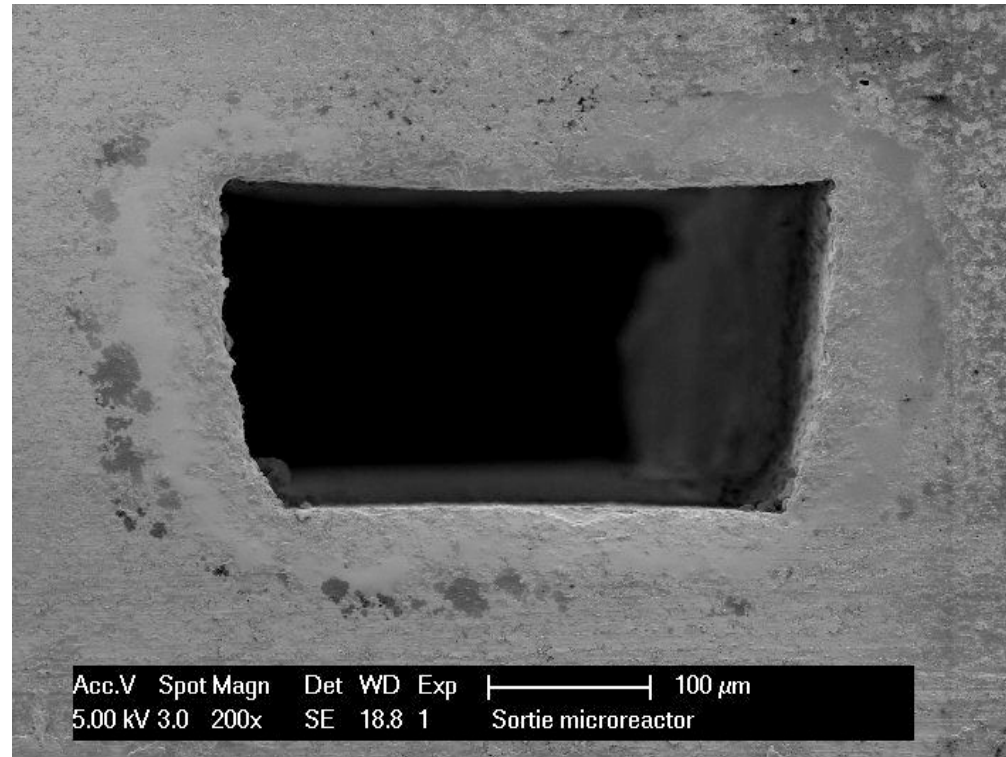
Microreactor - microscopy (3)

- Meanders in reaction zone
- 2nd meander in other fluidics layer

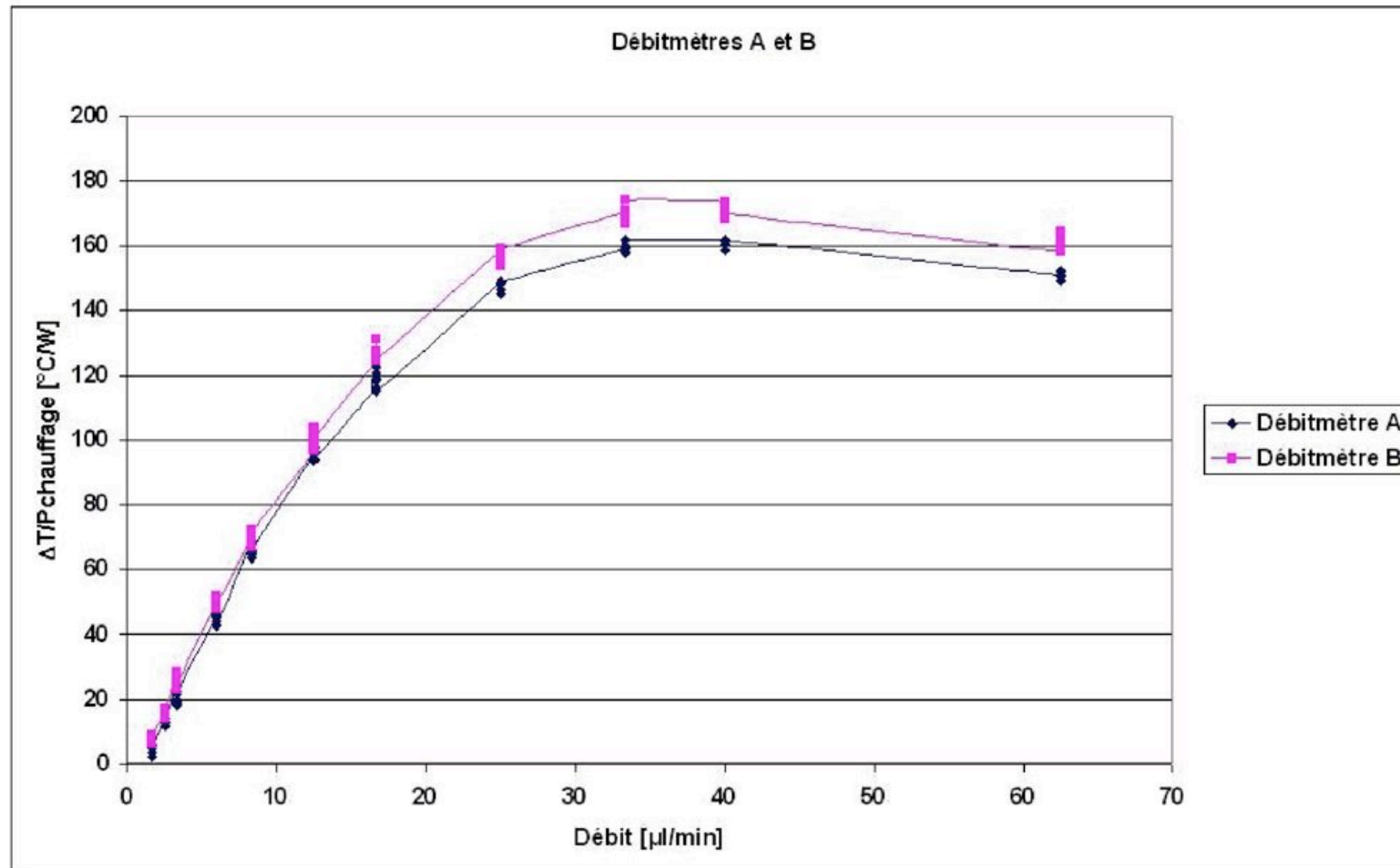


Microreactor - microscopy (4)

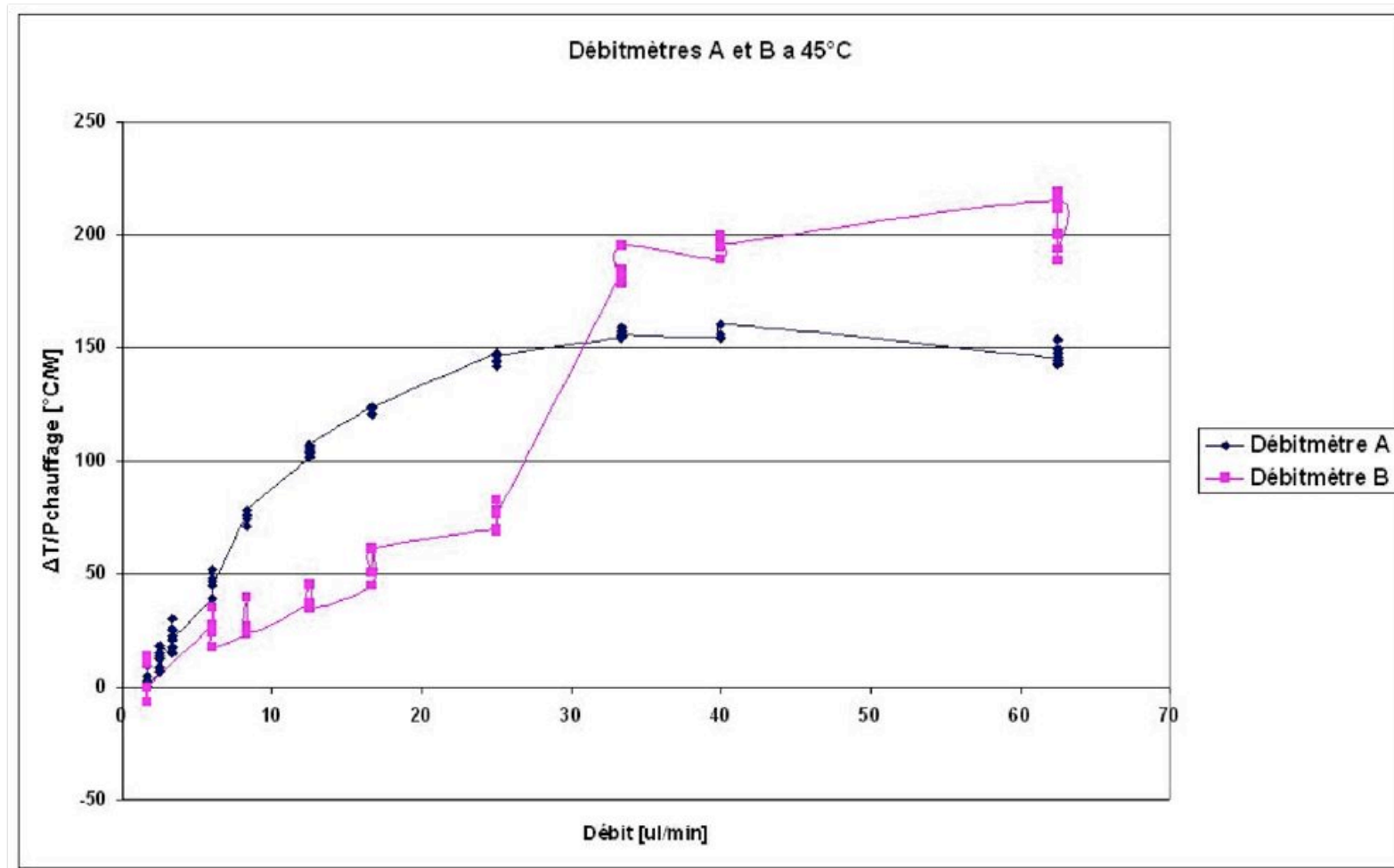
- Outlet channel + bridge



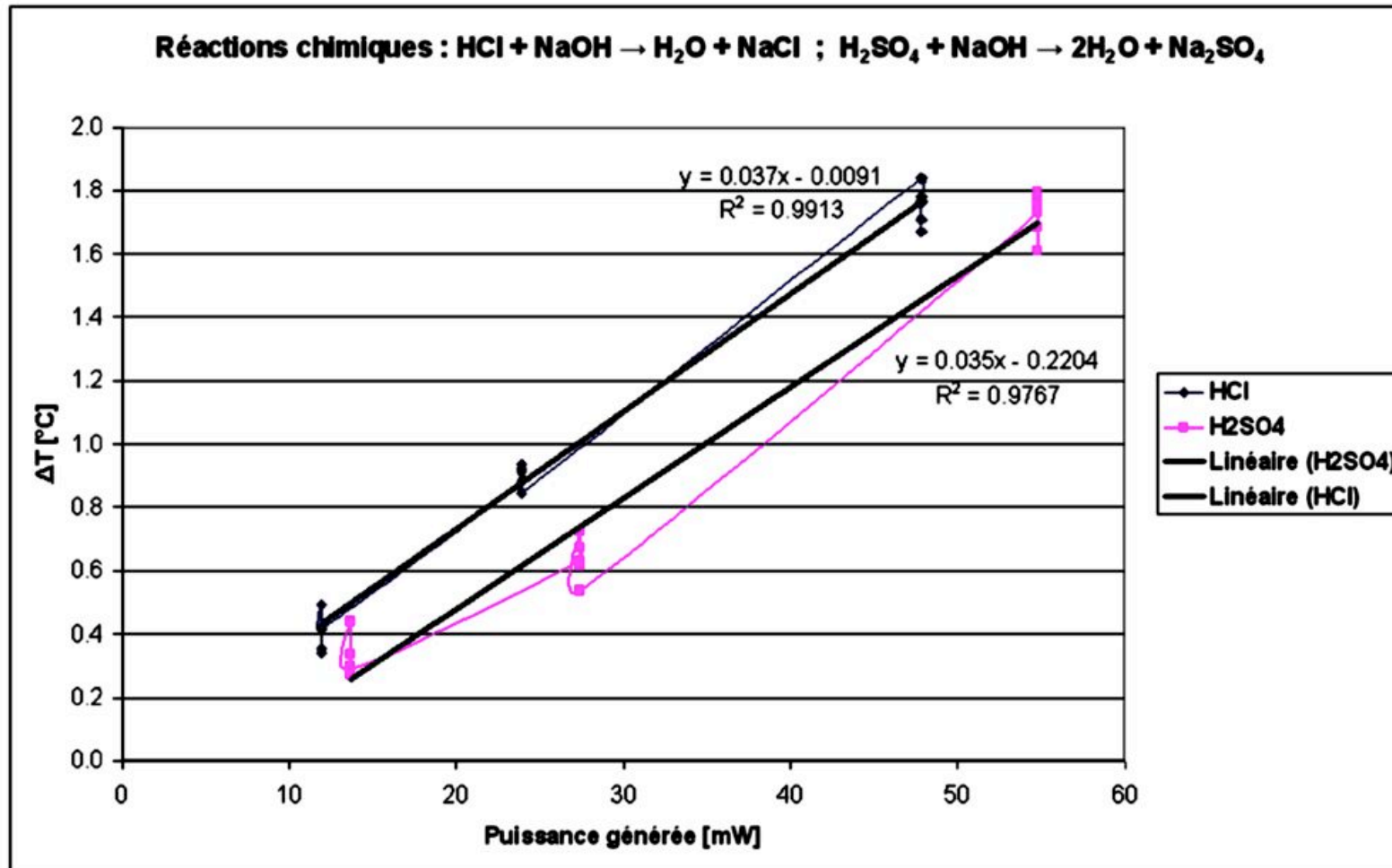
Characterisation - flowmeters @ RT



Characterisation - flowmeters @ 45°C



Characterisation - acid-base reactions



Conclusions

- Simple integrated device
- Low manufacturing cost
- Good stability
- Very flexible technology
- Suitable for both liquids & gases
- Boundary conditions not yet optimal

Outlook

Thermal design

- Use better heat spreaders: Ag, AlN
- Improve reactor boundary conditions
- Active preheat zones

Electronics & software

- Better adjustments
- More precise measurements

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- Raphaël Willigens
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THANK

YOU !